



## CyberOptics Launches Next Generation Airborne Particle Sensor (APS3) with New ParticleSpectrum™ Software

*Advances Leading Airborne Particle Sensing Technology Widely Adopted in Semiconductor Fabs Worldwide to Improve Yields and Tool Uptime*

**Minneapolis, MN— January 29, 2018** — CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces it will demonstrate its next generation Airborne Particle Sensor technology (APS3) 300mm with new ParticleSpectrum™ software at SEMICON Korea, January 31st through February 2nd at the Seoul COEX in booth # A418.

CyberOptics' WaferSense® APS3 speeds equipment set-up and long-term yields in semiconductor fabs by wirelessly detecting, identifying and monitoring airborne particles in real-time. CyberOptics' Airborne Particle Sensors, documented as the best known method (BKM), have proven to deliver up to 90% timesavings, 95% expense reduction and up to 20X the throughput with half the manpower relative to legacy surface scan wafer methods.



The APS3 measurement devices are even thinner and lighter to travel through semiconductor tools with ease, while providing the industry-leading accuracy and sensitivity valued by equipment and process engineers around the world. The APS3 solution incorporates ParticleSpectrum software – a completely new, touch-enabled interface with user-friendly functionality, making it simple to read in real-time, record and review small to large airborne particle data.

“Semiconductor fabs and equipment OEMs worldwide have relied on our proven airborne particle sensing technology to provide significant improvements in yields,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics. “Now, we’ve made the device even thinner and lighter and combined it with ParticleSpectrum, a software package that is sure to delight the engineers with its simplicity.”

At SEMICON Korea, CyberOptics will also unveil a new Airborne Particle Sensor designed for the Flat Panel Display (FPD) market.

### **About the WaferSense and ReticleSense Line**

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensors and the new Auto Multi Sensor (AMS), are available in various wafer shaped form factors depending on the device, including 150mm, 200mm and 300mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensors (APSR & APSRQ), the Auto Leveling System (ALSR) and the Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled AOI systems; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the success of CyberGage360; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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